

CLAIMS:

1. A package comprising:
a flexible substrate comprising a polymeric transparent film;
an organic electronic device coupled to the transparent film;
a sealant coupled to the flexible substrate and disposed about the
perimeter of the organic electronic device; and
a superstrate coupled to the sealant and disposed proximate to the organic
electronic device.
2. The package, as set forth in claim 1, wherein the flexible substrate
comprises the barrier coating.
3. The package, as set forth in claim 1, wherein the flexible substrate is a
composite substrate comprising:
a first protective layer configured to resist abrasion;
a polymeric transparent film coupled to the first protective layer;
a barrier coating coupled to the transparent film; and
a second protective layer coupled to the barrier coating and configured to
protect the transparent film from chemical attack during
fabrication.
4. The package, as set forth in claim 1, wherein the flexible substrate is a
composite substrate comprising:
a first protective layer configured to resist abrasion;
a first polymeric transparent film coupled to the first protective layer;
a first barrier coating coupled to the first transparent film;
a second barrier coating coupled to the first barrier coating via an
adhesive layer;
a second polymeric transparent film coupled to the second barrier
coating; and

a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

5. The package, as set forth in claim 1, comprising a barrier coating coupled between the flexible substrate and the organic electronic device.

6. The package, as set forth in claim 1, wherein the organic electronic device comprises an organic light emitting diode.

7. The package, as set forth in claim 1, wherein the organic electronic device comprises an organic photovoltaic device.

8. The package, as set forth in claim 1, wherein the sealant comprises an adhesive material having a low permeability.

9. The package, as set forth in claim 1, wherein the sealant comprises a thickness that is greater than a thickness of the organic electronic device.

10. The package, as set forth in claim 1, wherein the superstrate comprises a metal foil.

11. A package comprising:
a flexible substrate comprising a polymeric transparent film;
an organic electronic device coupled to the transparent film;
a sealant coupled to the transparent film and disposed about the perimeter of the organic electronic device; and
a superstrate coupled to the sealant and disposed proximate to the organic electronic device, wherein the superstrate comprises a periphery adapted to wrap around edges of the package such that the periphery of the superstrate is coupled to a side of the flexible substrate opposite the organic electronic device.

12. The package, as set forth in claim 11, wherein the flexible substrate comprises the barrier coating.

13. The package, as set forth in claim 11, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a polymeric transparent film coupled to the first protective layer;
- a barrier coating coupled to the transparent film; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

14. The package, as set forth in claim 11, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a first polymeric transparent film coupled to the first protective layer;
- a first barrier coating coupled to the first transparent film;
- a second barrier coating coupled to the first barrier coating via an adhesive layer;
- a second polymeric transparent film coupled to the second barrier coating; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

15. The package, as set forth in claim 11, comprising a barrier coating coupled between the flexible substrate and the organic electronic device.

16. The package, as set forth in claim 11, wherein the organic electronic device comprises an organic light emitting diode.

17. The package, as set forth in claim 11, wherein the organic electronic device comprises an organic photovoltaic device.

18. The package, as set forth in claim 11, wherein the sealant comprises an adhesive material having a low permeability.

19. The package, as set forth in claim 11, wherein the sealant comprises a thickness that is greater than a thickness of the organic electronic device.

20. The package, as set forth in claim 11, wherein the superstrate comprises a metal foil.

21. The package, as set forth in claim 11, comprising a desiccant material disposed within pockets formed by wrapping the edges of the package with the superstrate.

22. A package comprising:
a flexible substrate comprising a polymeric transparent film;
an organic electronic device coupled to the transparent film;
a sealant coupled to the transparent film and disposed about the perimeter of the organic electronic device;
a superstrate coupled to the sealant and disposed proximate the organic electronic device; and
an edge seal coupled to each of the flexible substrate and the superstrate and configured to hermetically seal peripheral edges of the package.

23. The package, as set forth in claim 22, wherein the flexible substrate comprises the barrier coating.

24. The package, as set forth in claim 22, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a polymeric transparent film coupled to the first protective layer;
- a barrier coating coupled to the transparent film; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

25. The package, as set forth in claim 22, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a first polymeric transparent film coupled to the first protective layer;
- a first barrier coating coupled to the first transparent film;
- a second barrier coating coupled to the first barrier coating via an adhesive layer;
- a second polymeric transparent film coupled to the second barrier coating; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

26. The package, as set forth in claim 22, comprising a barrier coating coupled between the flexible substrate and the organic electronic device.

27. The package, as set forth in claim 22, wherein the organic electronic device comprises an organic light emitting diode.

28. The package, as set forth in claim 22, wherein the organic electronic device comprises an organic photovoltaic device.

29. The package, as set forth in claim 22, wherein the sealant comprises an adhesive material having a low permeability.

30. The package, as set forth in claim 22, wherein the sealant comprises a thickness that is greater than a thickness of the organic electronic device.

31. The package, as set forth in claim 22, wherein the superstrate comprises a metal foil.

32. The package, as set forth in claim 22, comprising a desiccant material disposed within pockets formed by the edge seal.

33. The package, as set forth in claim 22, wherein the edge seal comprises a metal foil.

34. A package comprising:

- a first composite substrate, wherein peripheral edges of the first composite substrate are covered with a first edge seal;
- a second composite substrate, wherein peripheral edges of the second composite substrate are covered with a second edge seal; and
- an organic electronic device disposed between the first composite substrate and the second composite substrate, wherein the first composite substrate is coupled to the second composite substrate via a sealant.

35. The package, as set forth in claim 34, wherein each of the first composite substrate and the second composite substrate comprises:

- a first protective layer configured to resist abrasion;
- a polymeric transparent film coupled to the first protective layer;
- a barrier coating coupled to the transparent film; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

36. The package, as set forth in claim 34, wherein each of the first composite substrate and the second composite substrate comprises:

- a first protective layer configured to resist abrasion;
- a first polymeric transparent film coupled to the first protective layer;
- a first barrier coating coupled to the first transparent film;
- a second barrier coating coupled to the first barrier coating via an adhesive layer;
- a second polymeric transparent film coupled to the second barrier coating; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

37. The package, as set forth in claim 34, wherein the organic electronic device comprises an organic light emitting diode.

38. The package, as set forth in claim 34, wherein the organic electronic device comprises an organic photovoltaic device.

39. The package, as set forth in claim 34, wherein the sealant comprises an adhesive material having a low permeability.

40. The package, as set forth in claim 34, comprising a desiccant material disposed within pockets formed by each of the edge seals.

41. The package, as set forth in claim 34, wherein each of the edge seals comprises a metal foil.

42. A method of fabricating a package comprising:
- providing a roll of a flexible substrate film;
 - disposing a plurality of organic devices on the flexible substrate film;

providing a roll of metal foil, the roll of metal foil having approximately the same dimensions as the roll of flexible substrate film;
disposing a sealant on the metal foil such that the sealant is arranged to form a plurality of perimeters, wherein each of the plurality of perimeters is sized to completely surround the organic devices once the metal foil is coupled to the flexible substrate film; and
coupling the metal foil to the flexible substrate film.

43. The method, as set forth in claim 42, comprising excising each of the plurality of packages.

44. The method, as set forth in claim 43, wherein excising comprises cutting the metal foil such that the metal foil on each of the plurality of packages has a larger surface area than a surface area of the flexible substrate film.

45. The method, as set forth in claim 44, comprising wrapping the metal foil around the entire periphery of the flexible substrate film.

46. The method, as set forth in claim 43, comprising coupling an edge seal to the excised package, wherein the edge seal is configured to hermetically seal peripheral edges of the package.